

Appvion, LLC · 825 East Wisconsin Avenue · Appleton, Wisconsin 54912 · (877) 768 – 8399 ·

appvion.com

APPVION

Résiste[®] 165 E



Label Facestock



Key Features

- Made with our industry-leading, patent-pending, phenol-free direct thermal chemistry
 - Unmatched resistance to fading
 - Aquatic-friendly
- Lower energy required to print high-contrast images
- Improved resistance to heat, water, and alcohol

IN USA

- · Imaging speed up to 8 ips
- · Repulpable

Applications

- [.] Package Delivery Labels
- · Logistics Labels

Résiste® 165 E is a topcoated direct thermal label facestock that was specifically designed with our patent-pending phenol-free direct thermal chemistry to revolutionize package delivery and logistics direct thermal label production with enhanced end-user performance and value.

Product Characteristics – Provisional Data

Caliper	3.0 +/- 0.2 mils 76.2 +/- 5 μm
Basis Weight 17 x 22–500 (lbs) g/m2	19.0 +/- 1.4 71.6 +/- 3.4
Thermal Response - Nominal Static (°C ± 5°) Initial Activation Temperature 0.2 ODU 1.0 ODU Maximum Density (ODU) Temperature Required	113° C, 236° F 133° C, 272° F 1.36 148° C
Dynamic—Atlantek 400 (mJ/mm2) Initial Printer Energy 0.2 ODU 1.0 ODU Maximum Density (ODU) Energy Required	6.1 9.7 1.6 16.0
Brightness (UV Excluded)	86.92
Gurley Stiffness Nominal (mg)	MD 90 CD 35
Elmendorf Tear Nominal (g)	MD 45 CD 45
Tensile (lbs/in)	MD 37 CD 17
Parker Print Surface	<1.15





